ADVANCING U.S. LEADERSHIP IN SEMICONDUCTOR INNOVATION

Chip design is key to driving innovation, but global competitors are challenging U.S. leadership. To ensure the U.S. is a competitive destination for companies to invest in semiconductor R&D, Congress should enact a 25% investment tax credit for chip design.

IMPORTANCE OF SEMICONDUCTOR DESIGN

Chip design is a critical R&D activity driving the function and value of a semiconductor device, enabling chips to receive, transmit, process, and store ever-increasing amounts of data for today's digital world. Design is a highly complex, interdisciplinary process involving years of R&D, hundreds of millions of dollars of investment, and thousands of engineers.

The semiconductor industry is R&D intensive, with U.S. chip companies investing on average 20% of revenue back into R&D, the second highest investment by any sector. As technology advances and design costs rise, a 25% investment tax credit for semiconductor design would ensure a holistic, integrated strategy to attract investment and provide predictable incentives to uphold U.S. leadership in chip design.

DESIGN LEADERSHIP IS TECHNOLOGY LEADERSHIP

- Technology Breakthroughs. Advances in chip design lead to innovation in semiconductor-enabled technologies that are the driving force behind 21st century U.S. economic and technology leadership.
- First Mover Advantage. Design leadership gives the U.S. a technological edge to be the "first mover," resulting in economic and national security benefits and greater influence in shaping international standards.
- Security and IP Control. U.S. design leadership ensures software, services, and products are based on U.S.-originated semiconductor IP, which lowers the risk of malicious tampering and enhances cybersecurity.















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Defense





Energy

Agriculture

CHALLENGES TO U.S. DESIGN LEADERSHIP

U.S. companies are currently the global leaders in design, but challenges are on the horizon - foreign governments are incentivizing chip design and R&D and seeking to supplant U.S. leadership.

1. Incentives for semiconductor R&D in the U.S. are weaker than our global competitors



2. Global competitors have targeted and enhanced incentives for semiconductor design and R&D

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China

- 220% super deduction for semiconductor R&D
- \$7B in funding for design firms from National IC Fund
 Revamped stock market rules resulting in \$50B of IPOs for fabless firms
- Corporate income tax exemption for key design

Taiwan

- 25% tax credit on chip R&D
- \$9B "Semiconductor Industrial Innovation Program"

Vietnam

• 150% of actual R&D costs as deductible expenses

Korea

- Up to 50% credit for semiconductor R&D
- Establishment of "Korean Fabless Valley"
- \$1.3B for AI and power chip design

Europe

- Italy: 25-100% credit for semiconductor R&D
 - **Spain:** \$1.4B in funding for chip design
- UK: \$1.2B in funding for semiconductor R&D

Singapore

• Up to 50% credit for high-value activities, including semiconductor R&D

India

• Up to 50% credit for design

Japan

- \$6B for Rapidus to establish 2nm technology
- \$960M for R&D of nextgeneration silicon

U.S.

- No enhanced semiconductor R&D or design credits
- 5-year amortization of R&D

Source: SIA analysis of government policies, company statements, and news reports.

3. Innovation costs are rising



65nm 40nm 28nm 22nm 16nm 10nm 7nm 5nm 3nm 2006 2008 2011 2012 2014 2017 2018 2020 2023

Source: <u>BCG</u>

5. Foreign growth in startups

Since 2013, China has substantially increased its share of investment deals in chip design firms, overtaking the U.S for the first time in 2018. The number of Chinese private equity and venture capital deals for fabless companies is now double that of the U.S.

4. Competition in scientific papers

Trends in papers accepted for presentation at the International Solid-State Circuits Conference (ISSCC) provide a barometer for global chip R&D leadership. In 2023, China's share of accepted papers eclipsed the U.S. share for the first time. The share of papers from the U.S. dropped by roughly 50% since 2017. Share of accepted papers at ISSCC



Source: ISSCC, the toremost global forum tor presentation of advances in solid-state circuits and systems-on-a-chip. Prof. Michael Flynn, University of Michigan Prof. Melissa Appleyard, Portland State University

Share of private equity and venture capital deals in chip design companies



AMERICA MUST COMPETE OR RISK BEING LEFT BEHIND

Congress should enact a 25% investment tax credit for semiconductor design

to advance U.S. innovation leadership

